

**Amendments to the Specification:**

Please replace the paragraph at page 10, line 29 - page 11, line 13 of the specification with the following amended paragraph:

In cross section (Figures 5a and 5b), the nozzle plate 21 is disposed on the heater chip 251. In turn, the heater chip attaches to the body 163 of the inkjet printhead 101. The lead beams 35 of the TAB circuit extend from the body 163 to electrically and physically attach with the heater chip 251 ~~[[321]]~~. A KAPTON cover 37 overlies a portion of the lead beams 35. Finally, an encapsulant bead 25 overlies the lead beam 35 to physically and electrically protect it. In one embodiment, the encapsulant bead is an ultraviolet cured epoxy sold as UV 9000 by Emerson & Cummings or 502-39-1 sold by EMS. Preferably, the encapsulant bead 25 extends from the KAPTON cover 37 to the surface 41 of the nozzle plate. In alternate embodiments, the encapsulant bead follows the contour of the dashed line 43 or other. The tape 11 overlies the surface of the nozzle plate 21 and seals the nozzle holes 23 shut for shipping. Preferably, the periphery of the tape does not touch any portion of the encapsulant bead. The tape may also embody a two layer structure having a poly vinyl chloride layer 51 over an acrylic layer 53. Preferably, it has an overall thickness of 75 microns +/- 10 microns.

Please replace the paragraph at page 11, line 14 - page 11, line 25 of the specification with the following amended paragraph:

At this point, skilled artisans should appreciate that the invention enables the encapsulant bead 25 to become closer to any of the nozzle holes 23 than previously known. In one embodiment, the leading edge 61 of the encapsulant bead resides on the nozzle plate

in a distance D1 from an edge 63 of a closest nozzle hole 23 of less than about 500 microns. In other embodiments, the distance D1 ranges between about 100 to about 400 microns with a more preferred range of about 200 to about 300 microns. Consequently, the taping of nozzle holes relative to encroaching encapsulant beads no longer serves as a limit on the heater chip 251 [[321]]. Thus, the heater chip 251 [[321]] may now have a smaller area, especially a shorter width W and length (not shown) thereby saving on silicon expenses. In turn, the nozzle plate width and length may correspondingly shrink.